Device processing facility for functional materials

Purpose:

This clean room facility is aimed for processing functional materials; such as SiC crystal, organic, super-conductor and new ceramic materials; to develop SiC power semiconductor, organic semiconductor and super-conductor devices, and various functional devices for power system operation.

Outlines:

- (i) This facility is equipped with multi-purpose clean rooms and device processing equipment for various functional materials.
- (ii) This facility enables high-resolution device processing for SiC semiconductor, organic semiconductor, super-conductor and new ceramic materials.
- (iii) The processed materials will be characterized by various material and electrical analysis equipment and demonstrate device functions and performance.

Specifications:

(i) Multi-purpose clean room

area: 14m x 14m

cleanliness: class 100-5000

(ii) Device processing equipment

plasma-etching, thin-film formation, high-temperature annealing furnace

Location and Date of Installation:

Yokosuka Area, February 2008

